

FORM PTO-1449 (Modified) INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)	Docket No. 378-21-034	Application Number 10/655,904
	Applicant James D. Parsons	
	Filing Date	Group Art Unit 2878

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number							Date	Name	Class	Subclass	Filing Date If Appropriate
OG	6	2	3	9	4	3	2	05-2001	Parsons	250	338.1	
OG	5	1	2	2	6	6	8	06-1992	Kajiura et al.	338	18	
OG	5	8	6	8	4	9	7A	02-1999	Jung	374	179	
OG	5	0	2	5	2	4	3A	06-1991	Ichikawa	338	19	
OG	4	6	9	5	7	3	3A	09-1987	Pesavento	250	551	

FOREIGN PATENT DOCUMENTS

	Document Number							Date	Country	Class	Subclass	Translation	
												Yes	No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

OG	1.	DE VASCONCELOS E A ET AL: "Highly sensitive thermistors based on high-purity polycrystalline cubic silicon carbide" SENSORS AND ACTUATORS A, ELSEVIER SEQUOIA S.A., LAUSANNE, CH, Vol. 83, no. 1-3, May 2000 (2000-05), pages 167-171, XP004198310 ISSN: 0924-4247
OG	2	DE VASCONCELOS E A ET AL: "Potential of high-purity polycrystalline silicon carbide for thermistor applications" JAPANESE JOURNAL OF APPLIED PHYSICS, PART 1 (REGULAR PAPERS, SHORT NOTES & REVIEW PAPERS), SEPT. 1998, PUBLICATION OFFICE, JAPANESE JOURNAL APPL. PHYS, JAPAN, vol. 37, no. 9A, pages 5078-5079, XP002211060 ISSN: 0021-4922
OG	3	Materials for High Temperature Semiconductor Devices: Committee on Materials for High-Temperature Semiconductor Devices, National Materials Advisory Board, Commission on Engineering and Technical Systems, National Research Council: National Academy Press, Washington, D.C., 1995, pp.68-70.
OG	4	O. Nennwitz, L. Spiess and V. Breternitz, "Ohmic Contacts to 6H-SiC", Applied Surface Science, Vol. 91, 1995, pages 347-351.
OG	5	J.A. Lely and P.A. Kroeger, "Electrical Properties of Hexagonal SiC Doped with N, B or Al", In Semiconductors and Phosphors, Proceedings of Intl. Colloquium-Partenkirchen, Ed. M. Schoen and H. Welker, New York, Interscience Pub., Inc. 1958, pp. 525-533.
OG	6	Q.Y. Tong, U. Gosele, C. Yuan, A.J. Steckl & M. Reiche, "Silicon Carbide Wafer Bonding", J. Electrochem Soc., Vol. 142, No. 1, January 1995, pp. 232-236.

Examiner <i>Olaf Gahr</i>	Date Considered 05/02/05
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

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OG OG	7	Choyke, W.J., "Optical and Electronic Properties of SiC" NATO ASI Series Vol. "The Physics and Chemistry of Carbides, Nitrides and Borides", Manchester, England, pp. 1-25, 9/18-22, 1999
	8	Spitzer et al., "Infrared Properties of Hexagonal Silicon Carbide", Physical Review, Vol. 113, No. 1, pp. 127-132, January 1, 1959.
OG	9	Electronic Properties Information Center, "Silicon Carbide", Hughes Aircraft Company, June 1965, pp. 9-16.
OG	10	P.K. Bhattacharya, "Bonding of SiC Slabs for Electro-Mechanical Heat-Sinks in Advanced Packaging Applications", J. Electronics, Vol. 73, No. 1, 1992, pp. 71-83.
OG	11	Westinghouse Astronuclear Laboratory "Silicon Carbide Junction Thermistor", 1965
OG	12	Jeffrey B. Casady et al, "A Hybrid 6H-SiC temperature Sensor Operational from 25°C to 500°C, IEEE Transactions on Components, Packaging and Manufacturing Technology" - Part A, Vol. 19, No. 3 (September 1996, pp 416-422.

Examiner	<i>Phil Gabe</i>	Date Considered	<i>03/25/05</i>
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